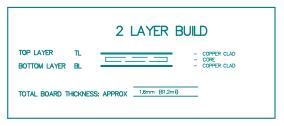
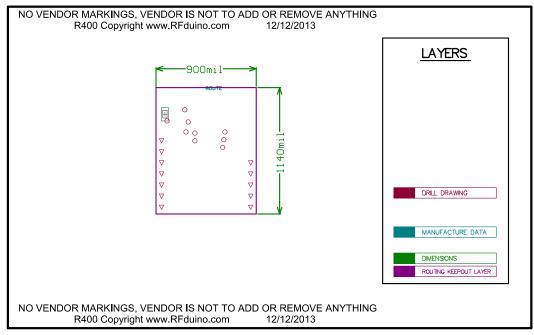


LAYER STACK CONFIGURATION





NOTES: UNLESS OTHERWISE SPECIFIED

- 1. MATERIAL: FR4
- 2. FINISH: BLACK GLOSS LPI SOLDERMASK OVER BARE COPPER, BOTH SIDES OF BOARD ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH SOLDER MASK OR OTHER PLATING SHALL BE PLATED WITH IMMERSION GOLD
- SILKSCREEN BOTH SIDES USING THE WHITE NON-CONDUCTIVE EPOXY INK, SILKSCREEN INC NOT ALLOWED ON COMPONENT PADS
- 4. NO VENDOR MARKINGS OF ANY TYPE, ON ANY LAYER OF THE PCB
- IT IS OK FOR VENDOR TO PUT MARKINGS ON THE RAILS OF THE ARRAY ONLY
- 5. IMPEDANCE CONTROL REQUIREMENT
- 6. FINISHED FAB AND WORKMANSHIP PER IPC-A-600, CLASS2
- 7. RoHS COMPLIANCE REQUIRED
- 8. ALL VIAS ARE TO BE FULLY PLUGGED WITH SOLDERMASK
- 9. IF THERE ARE ANY DISCREPANCIES, IT IS THE VENDORS RESPONSIBILITY TO CONTACT THE CUSTOMER 10. NO X-OUTS
- 11. 100% ELECTRICAL TEST FOR OPEN AND CLOSED REQUIRED

Symbol	Hit Count	Tool Size	Plated	Hole Type
0		28mil (0.711mm)		Round
∇	12	40mil (1.016mm)	PTH	Round
	21 Total			

